

IN THE CLAIMS:

Claims 1 through 19 and 29 through 34 were previously cancelled. None of the claims have been amended herein. All of the pending claims are presented below for convenience of the Examiner. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as previously amended.

1.-19. (Cancelled)

20. (Previously presented) A method for fabricating a semiconductor card, comprising:
providing a strip comprising a module with a peripheral opening defining an internal substrate and an external frame, and a plurality of connecting segments connecting the substrate to the frame, the substrate comprising a circuit side having a circuit thereon and a back side having external contacts thereon;
mounting at least one semiconductor component to the circuit side in electrical communication with the external contacts;
installing the strip in a molding assembly having a molding cavity with internal surfaces in first and second mold plates and wherein the substrate is forcibly moved to a level differing from the level of the frame;
molding a plastic body on the circuit side of the substrate, the body including edge portions of the card formed laterally outwardly from the substrate, and a plurality of wings extending laterally outwardly from the edge portions; and
removing the molded casting from the molding assembly and singulating the card from the wings by excision.

21. (Previously presented) The method in accordance with claim 20, wherein the substrate is moved to a level at which the back side thereof abuts a surface of the molding cavity.

22. (Previously presented) The method in accordance with claim 20, wherein the substrate is moved a distance of about 0.2 - 3 times the substrate thickness.

23. (Previously presented) The method in accordance with claim 20, wherein the substrate is moved by movement of pins passing through down-set throughholes in the molding assembly and wings to contact, move and clamp the connecting segments attached to the substrate.

24. (Previously presented) The method in accordance with claim 20, wherein portions of the peripheral opening adjacent outer ends of the connecting segments are elongated laterally outward to lengthen the connecting segments.

25. (Previously presented) The method in accordance with claim 20, wherein the frame is connected by connecting segments to the substrate on opposing edges thereof.

26. (Previously presented) The method in accordance with claim 20, wherein the molding encapsulates the circuit side of the substrate and leaves the external contacts uncovered.

27. (Previously presented) The method in accordance with claim 23, wherein the molded casting is removed from the molding assembly by inserting pins into the down-set throughholes to eject the molded casting thereby.

28. (Previously presented) The method in accordance with claim 23, wherein the molded casting is removed from the molding assembly by further insertion of the down-set pins through the down-set throughholes to eject the molded casting thereby.

29.-34. (Cancelled)